



Materials Analysis Technology Inc.

1F, No. 26-2, Tai-Yuan St., Jubai City, Hsinchu County, Taiwan 302, R.O.C.
WWW.MA-TEK.COM TEL:+886.3.5626678 FAX:+886.3.6005883

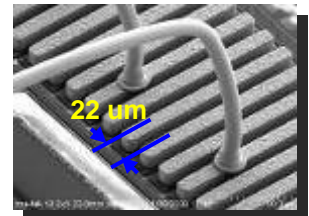
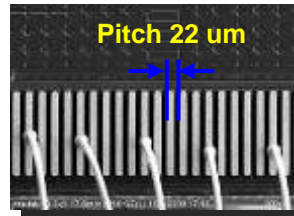
Independent/Professional Analysis Lab, the best partner to your R&D group!!
Your first choice to product development, quality assurance and IP strategy!!!

Total Solution of Wire Bonding

Applications :

- ✓ Chip-on-board, COB, bonding
- ✓ Stacked dice / Multi PCB
- ✓ High lead counts
- ✓ Electroless Ni/Au, ENIG
- ✓ Re-bonding of COF and COG

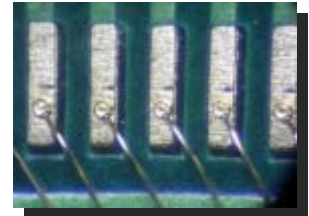
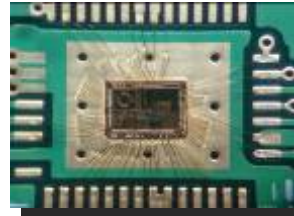
Ultra Fine Pitch Au Wire-bonding – 22 μ m



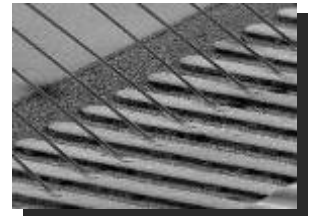
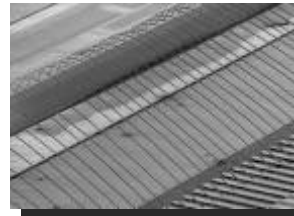
We provide :

- ✓ High quality and stable bonding services
- ✓ Fast cycle time : < 3 working days delivery
- ✓ High flexibility for customer
- ✓ Total solutions: die saw, die mount, Al/Au wire-bonding, pull/shear test, fast packaging, SAT / X-ray inspection, electrical verification, etc.

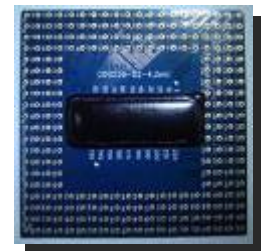
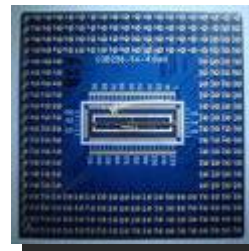
Au Wire-bonding on Electroless Ni/Au Board



Al Wire-bonding



MA-tek Bonding Board Template



Case Log-in, please call:

Technical: Mr. Eric Gu

Tel: 886-966-301-629

E-mail: eric_gu@ma-tek.com

Sales: Ms. Midori Nakamura

Tel: 886-966-350-603

E-mail: midori@ma-tek.com

You are highly welcome to use Fedex (account no. 2665-9953-6) , DHL (account no. 968368648) or UPS services for sample shipping. MA-tek will pay the courier charge upon sample arrival.



Proprietary, DO NOT COPY WITHOUT PERMISSION

The content of this report is ONLY valid to the case of corresponding report number. Any page, or pages, of this report can not be used separately.